

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Akihiko ENDO et al.

Confirmation No.: 1241

Appln. No. : 10/570,665

Group Art Unit: 4158

(U.S. National Stage of PCT/JP2004/013067)

Examiner: Ming Hung HUNG

I.A. Filed : September 8, 2004

For : BONDED WAFER AND ITS MANUFACTURING METHOD

SUPPLEMENTAL AMENDMENT UNDER 37 C.F.R § 1.111

Commissioner of Patents
U.S. Patent and Trademark Office
Customer Service Window, Mail Stop Amendment
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

This Supplemental Amendment is responsive to the Office Action mailed April 8, 2008, and submitted to correct the "*Amendments to the Claims*" section of the Amendment under 37 C.F.R. § 1.111, filed July 8, 2008. Inasmuch as the Amendment under 37 C.F.R. § 1.111, filed July 8, 2008, was timely filed and is fully responsive to the Office Action, no extension of time is believed necessary. However, if any extension of time or other fees are necessary to maintain the pendency of this patent application, the Office is authorized to charge such fee to Deposit Account No. 19-0089.

Amendments to the Claims are reflected in the listing of claims, which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.